

Features

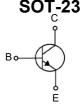
Collector Current: I_C=0.6A
 Power Dissipation of 300mw

1. BASE

2. EMITTER

3. COLLECTOR





Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
2N5551S-RTK/P	SOT-23	G1	3000

Maximum Ratings (Ta=25 unless otherwise noted)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CBO}	180	V
Collector-Emitter Voltage	V _{CEO}	160	V
Emitter-Base Voltage	V _{EBO}	6	V
Collector Current	I _c	600	mA
Collector Power Dissipation	P _c	300	mW
Thermal Resistance From Junction To Ambient	R _{OJA}	416	°CM
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55∼+150	℃

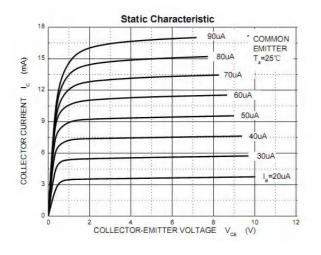
Electrical Characteristics(Ta=25 unless otherwise specified)

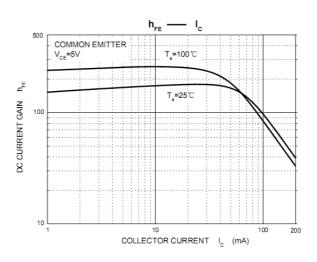
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	$V_{(BR)CBO}$	I _C =100μA, I _E =0	180			V
Collector-emitter breakdown voltage	V _{(BR)CEO} *	I _C =1mA, I _B =0	160			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	I _E =10μA, I _C =0	6			V
Collector cut-off current	I _{CBO}	V _{CB} =120V, I _E =0			50	nA
Emitter cut-off current	I _{EBO}	V _{EB} =4V, I _C =0			50	nA
DC current gain	h _{FE(1)} *	V _{CE} =5V, I _C =1mA	80			
	h _{FE(2)} *	V _{CE} =5V, I _C =10mA	100		300	
	h _{FE(3)} *	V _{CE} =5V, I _C =50mA	50			
Collector-emitter saturation voltage	V _{CE(sat)1} *	I _C =10mA, I _B =1mA			0.15	V
	V _{CE(sat)2} *	I _C =50mA, I _B =5mA			0.2	V
Base-emitter saturation voltage	V _{BE(sat)1} *	I _C =10mA, I _B =1mA			1	V
	V _{BE(sat)2} *	I _C =50mA, I _B =5mA			1	V
Transition frequency	f _T	V _{CE} =10V,I _C =10mA, f=100MHz	100		300	MHz
Collector output capacitance	C _{ob}	V _{CB} =10V, I _E =0, f=1MHz			6	pF

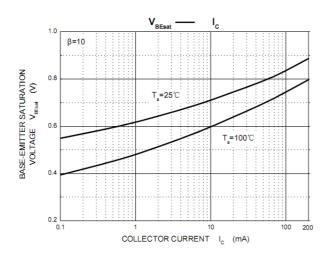
^{*}Pulse test: pulse width ≤300µs, duty cycle≤ 2.0%.

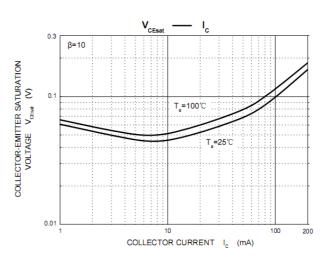


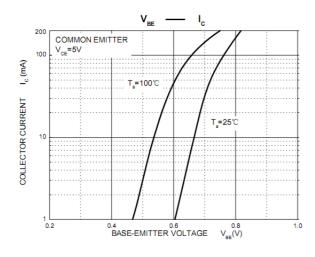
Typical Characteristics

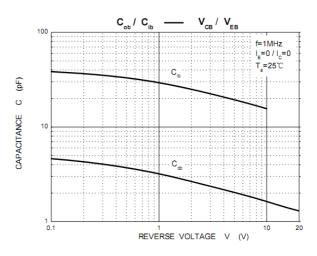


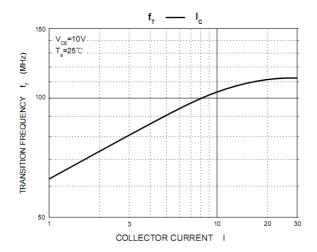


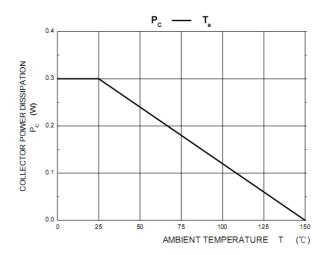






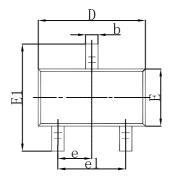


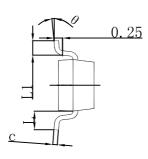


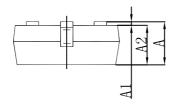




SOT-23 Package Outline Dimensions

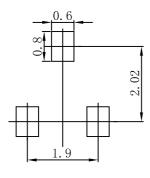






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.2.General tolerance:± 0.05mm.3.The pad layout is for reference purposes only.



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